

Rev.A Oct.-2025

SOT-523 P MOS

P-CHANNEL MOSFET in a SOT-523 Plastic Package.

$V_{DS}(V) = -20\text{ V}$ $I_D = -0.7\text{ A}$

$R_{DS(ON)} @ -4.5\text{ V} \leq 520\text{ m}\Omega$ (Typ. 400m Ω)

$R_{DS(ON)} @ -2.5\text{ V} \leq 780\text{ m}\Omega$ (Typ. 570m Ω)

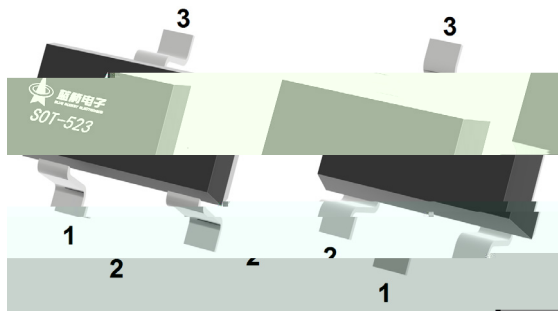
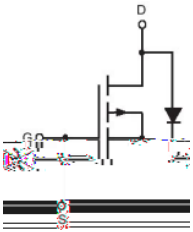
$R_{DS(ON)} @ -1.8\text{ V} \leq 1100\text{ m}\Omega$ (Typ. 810m Ω)

2KV ESD protected up to 2KV.

HF Product.

DC/DC

Load Switching, Low Current Inverters, Low Current DC/DC Converters.



PIN1 G

PIN 2 S

PIN 3 D

See Marking Instructions.

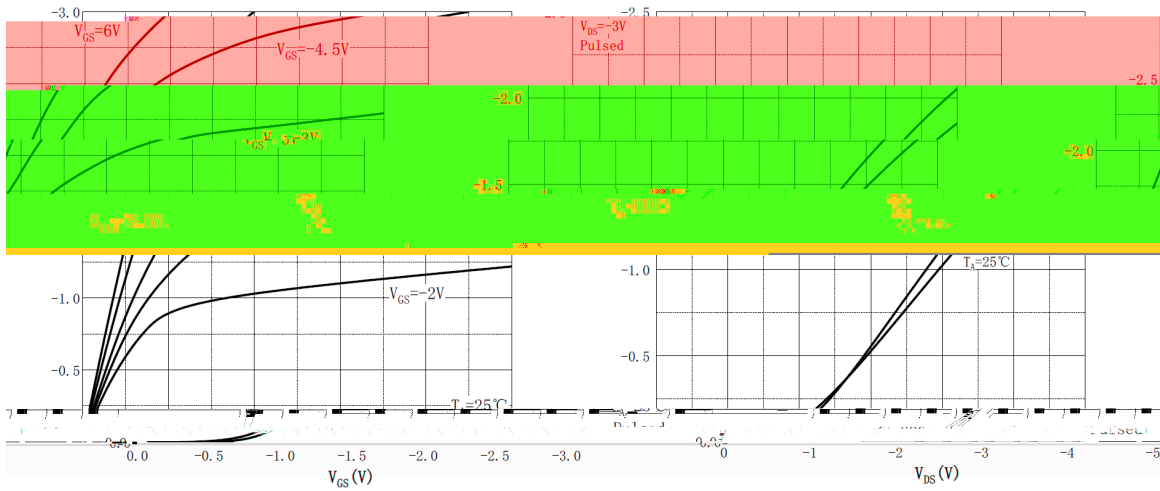


Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

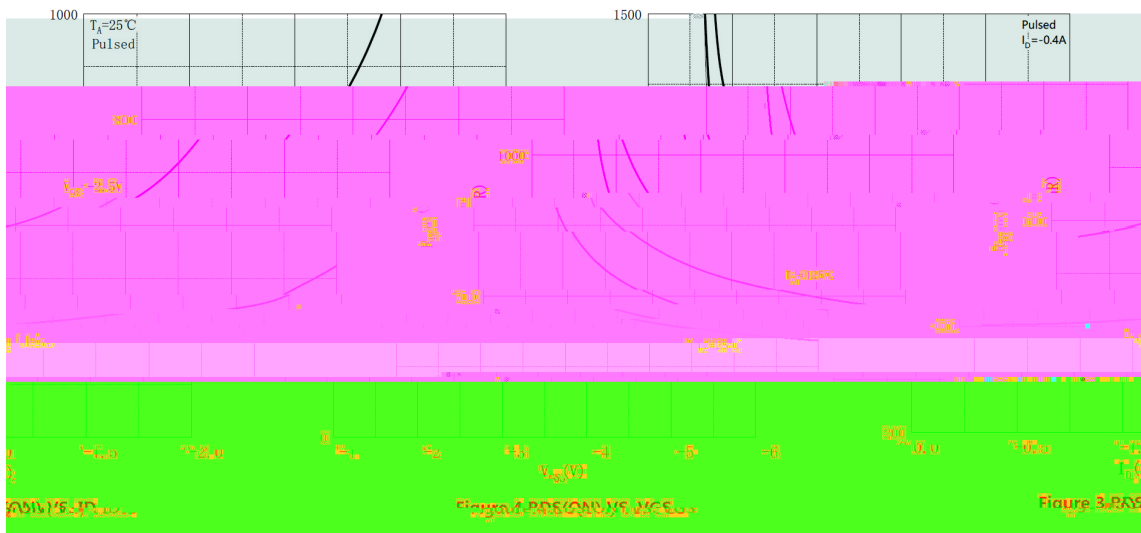


Figure 3. RDS(on)

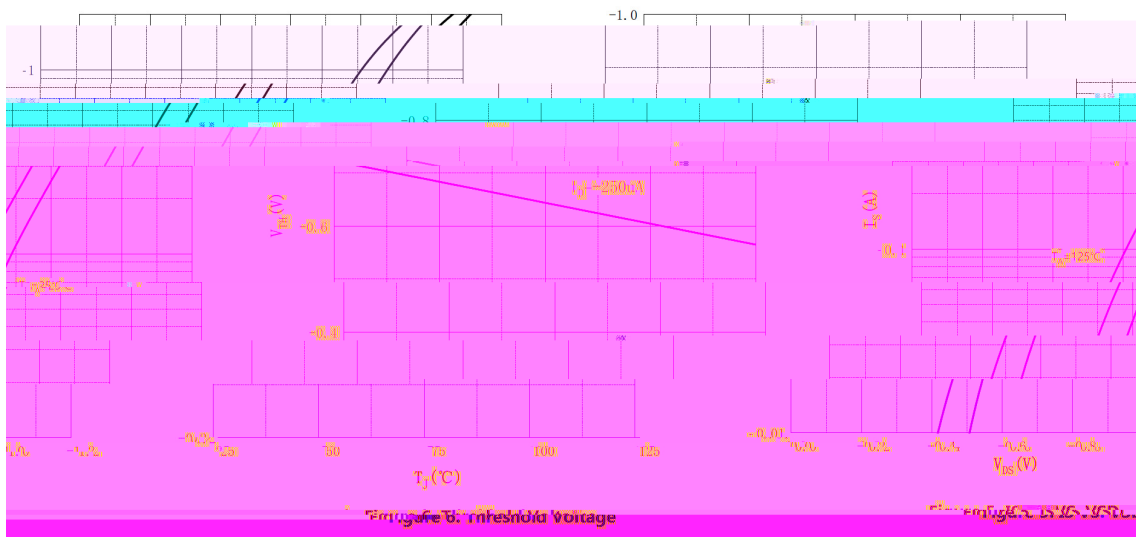
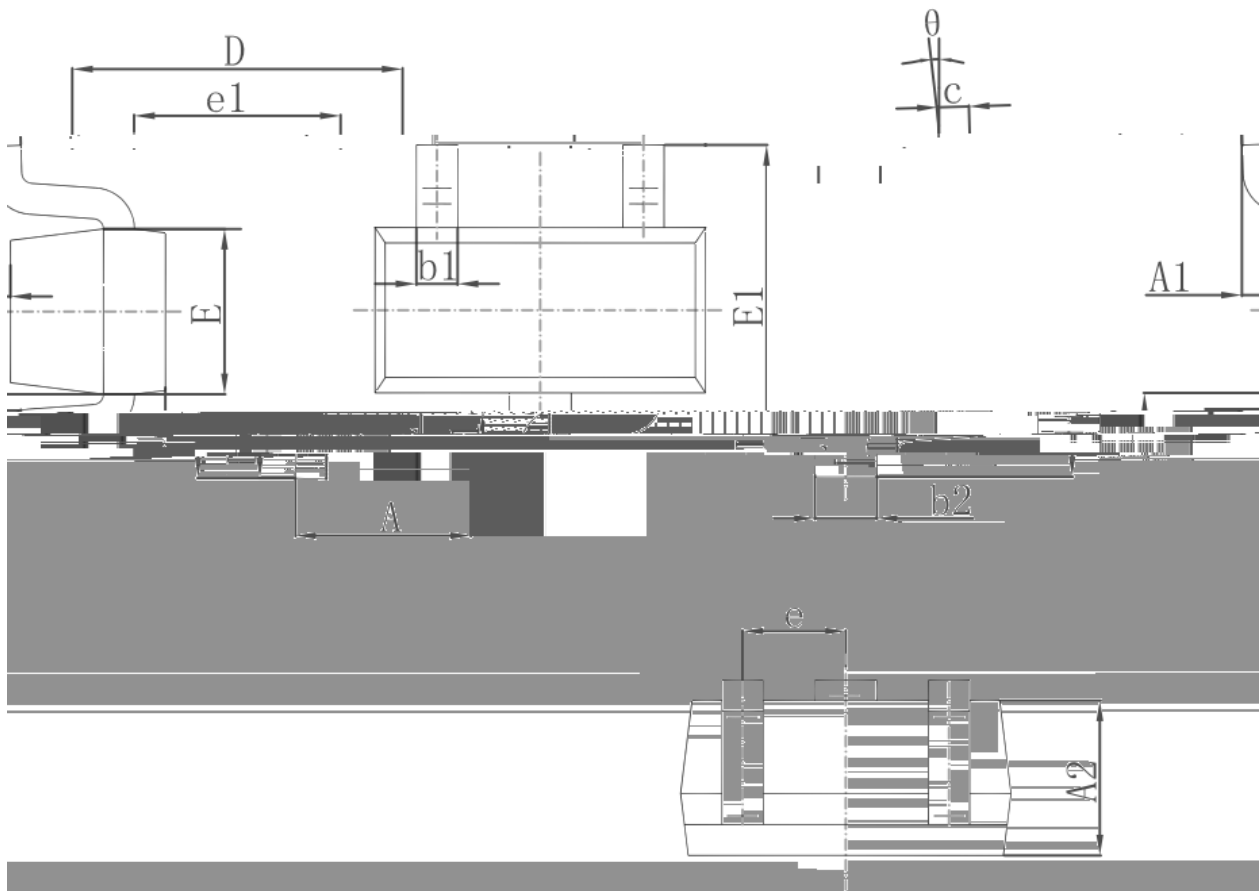
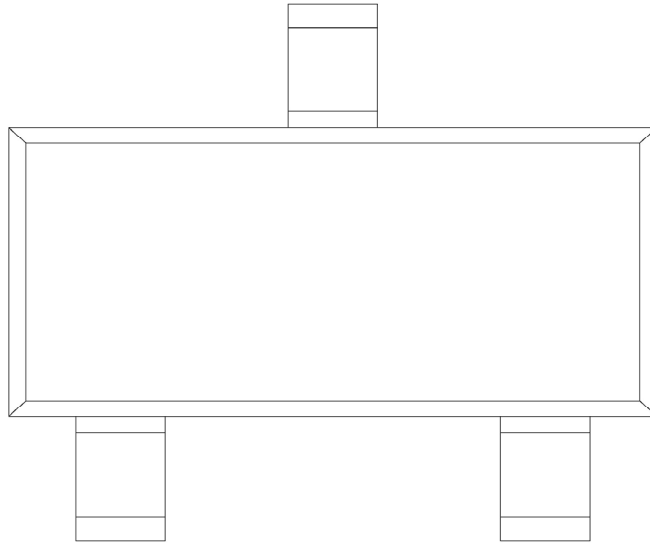


Figure 4. Threshold Voltage



Dimensions In Inches		Symbol	Dimensions In Millimeters	
Min.	Max.		Min.	Max.
0.028	0.035	A	0.700	0.900
0.000	0.004	A1	0.000	0.100
0.028	0.031	A2	0.700	0.800
0.010	0.014	b1	0.250	0.350
0.010	0.014	b2	0.250	0.350
0.010	0.014	c	0.250	0.350
0.010	0.014	D	0.250	0.350
0.010	0.014	E	0.250	0.350
0.010	0.014	E1	0.250	0.350
0.010	0.014	F	0.250	0.350
0.010	0.014	L	0.250	0.350
0.010	0.014	L1	0.250	0.350
0.010	0.014	θ	0°	8°



39K

Temperature Profile for IR Reflow Soldering(Pb-Free)

- Note:

11501806090sec;

2245±55±0.5sec;

3210/sec.

1.Preheating:150~180, Time:60~90sec.

2.Peak Temp.:245±5, Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

260±510±1 sec.Temp.:260±5Time:10±1 sec

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box